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Part Number: **0876232012**

Status: **Active**

Description: 1.27mm (.050") Pitch DDR DIMM Socket, Low Profile (25°), Single Key, with Beveled Metal Pins and Plastic Pegs, 3.18mm (.125") Tail Length, with 3.18mm (.125") Locating Pegs, 0.38µm (15µ") Gold (Au) Plating, 184 Circuits, Leadfree

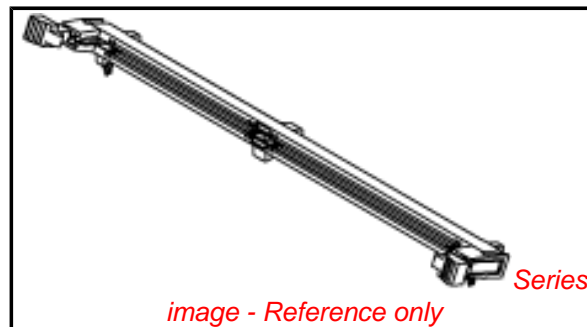
Documents:

[3D Model](#)

[Drawing \(PDF\)](#)

[Product Specification PS-87623-002 \(PDF\)](#)

[RoHS Certificate of Compliance \(PDF\)](#)



General

| | |
|----------------|-----------------------|
| Product Family | Memory Module Sockets |
| Series | 87623 |
| Component Type | Memory Module |
| JEDEC Outline | MO-206 |
| Product Name | DDR DIMM |

Physical

| | |
|--------------------------------|--------------------------------|
| Circuits (Loaded) | 184 |
| Color - Resin | Black, Natural |
| Durability (mating cycles max) | 25 |
| Entry Angle | 25° Angle |
| Keying to Mating Part | Yes |
| Material - Metal | Brass, Phosphor Bronze |
| Material - Plating Mating | Gold |
| Material - Plating Termination | Tin |
| Material - Resin | High Temperature Thermoplastic |
| PC Tail Length (in) | 0.125 In |
| PC Tail Length (mm) | 3.18 mm |
| PCB Locator | Yes |
| PCB Retention | Yes |
| PCB Thickness Recommended (in) | 0.062 In |
| PCB Thickness Recommended (mm) | 1.60 mm |
| Packaging Type | Tray |
| Pitch - Mating Interface (in) | 0.050 In |
| Pitch - Mating Interface (mm) | 1.27 mm |
| Plating min: Mating (µin) | 15.2 |
| Plating min: Mating (µm) | 0.38 |
| Plating min: Termination (µin) | 101.6 |
| Plating min: Termination (µm) | 2.54 |
| Temperature Range - Operating | -40°C to +85°C |
| Termination Interface: Style | Through Hole |

Electrical

| | |
|-------------------------------|------------|
| Current - Maximum per Contact | 1A |
| Voltage - Maximum | 50V |
| Voltage Key | 2.5V, Left |

Solder Process Data

| | |
|--|------------------------------|
| Duration at Max. Process Temperature (seconds) | 10 |
| Lead-free Process Capability | SMC & Wave Capable (TH only) |
| Max. Cycles at Max. Process Temperature | 2 |
| Process Temperature max. C | 260 |

Material Info

Reference - Drawing Numbers

EU RoHS

**ELV and RoHS
Compliant**

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Halogen-Free

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[87623Series](#)

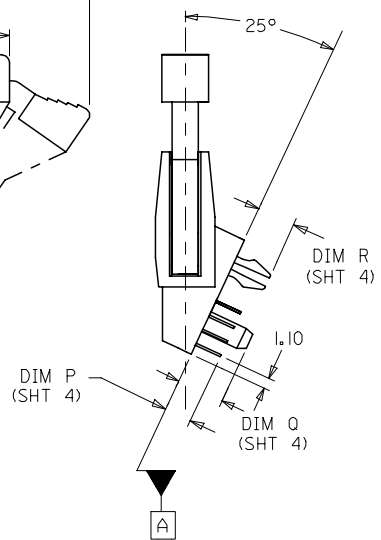
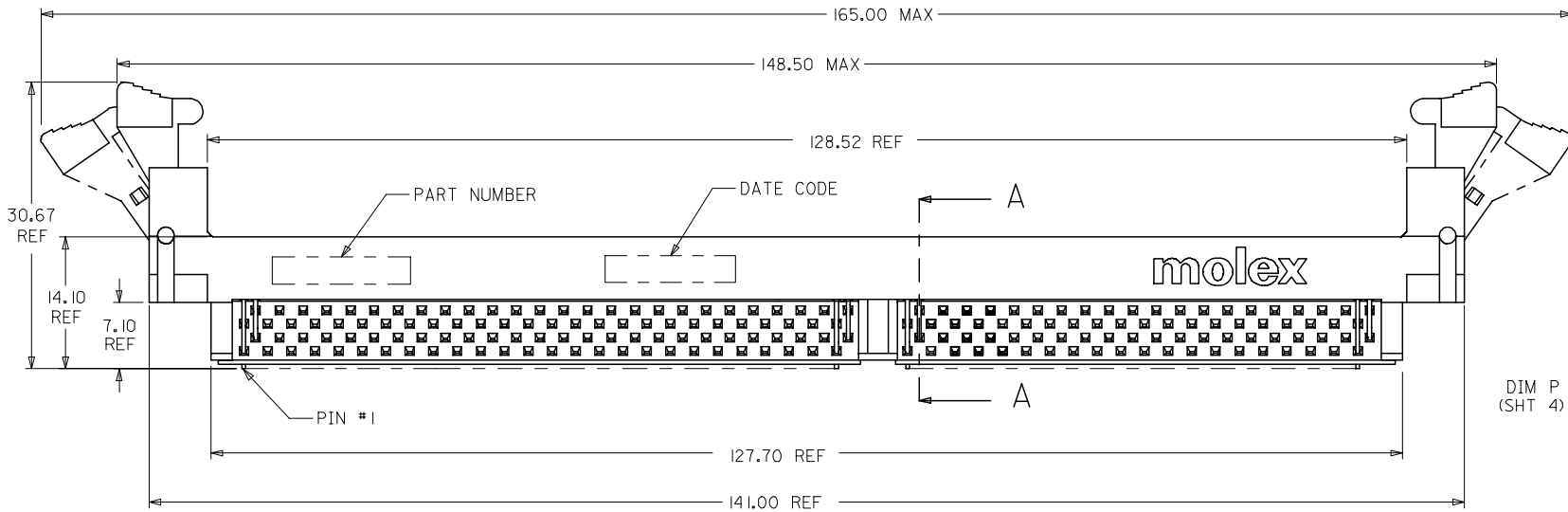
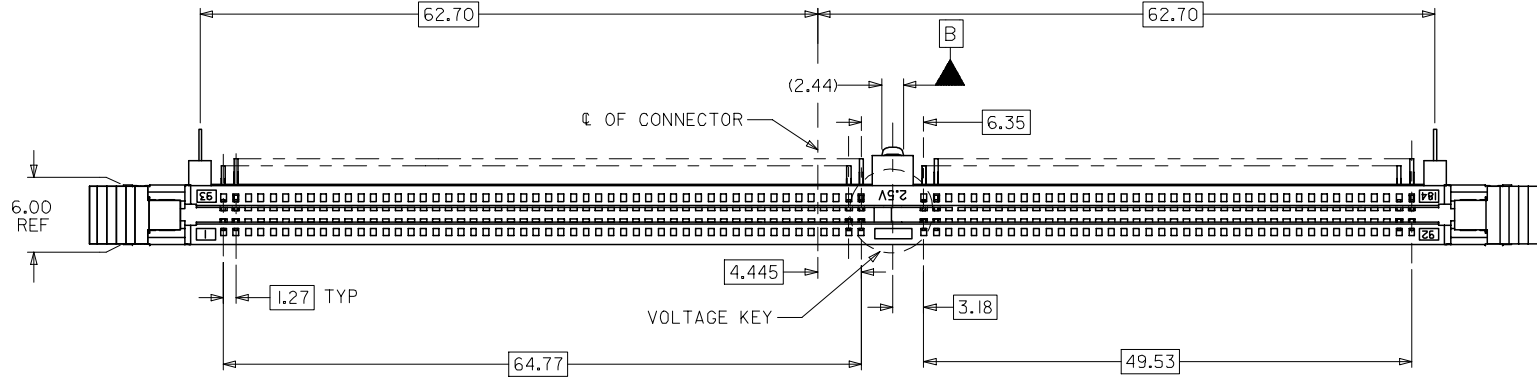
Mates With

JEDEC MO-206 modules

This document was generated on 04/09/2010

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10 9 8 7 6 5 4 3 2 1



- NOTES:
- MATERIALS: HOUSING & BASEPLATE - LCP, GLASS FILLED, UL 94V-0, COLOR: BLACK
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0, COLOR: BEIGE
TERMINAL AND FORKLOCK - COPPER ALLOY
 - FINISHES: CONTACT AREA: SEE TABLE ON SHEET 4
SOLDER TAILS: 2.54µm/100µ" MIN. TIN
OVER 1.27mm/50µ" MIN. NICKEL
 - PRODUCT SPECIFICATIONS: PS-87623-002 FOR PERFORMANCE SPECIFICATIONS.
 - DATE CODE SHALL BE MARKED LEGIBLY AS SHOWN: XX XX
YEAR — WEEK
 - PART NUMBER SHALL BE MARKED LEGIBLY AS SHOWN: 87623-0XXX
REFER TO TABLE

| | | | |
|------------------|-------------------|------------|-----------------|
| OBS TIN/LEAD P/N | EC NO: S2006-0734 | 2006/02/27 | QUALITY SYMBOLS |
| | DRWN:MLONG | 2006/02/28 | |
| | CHKD:HO | 2006/03/01 | |
| | APPR:GJLEE | | |
| REV | DESCRIPTION | | |

| | | |
|--|--|-------|
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | GENERAL TOLERANCES (UNLESS SPECIFIED) | |
| | mm | INCH |
| | 4 PLACES ± --- | ± --- |
| | 3 PLACES ± --- | ± --- |
| | 2 PLACES ± 0.25 | ± --- |
| 1 PLACE ± --- | ± --- | |
| | ANGULAR ± 5 ° | |

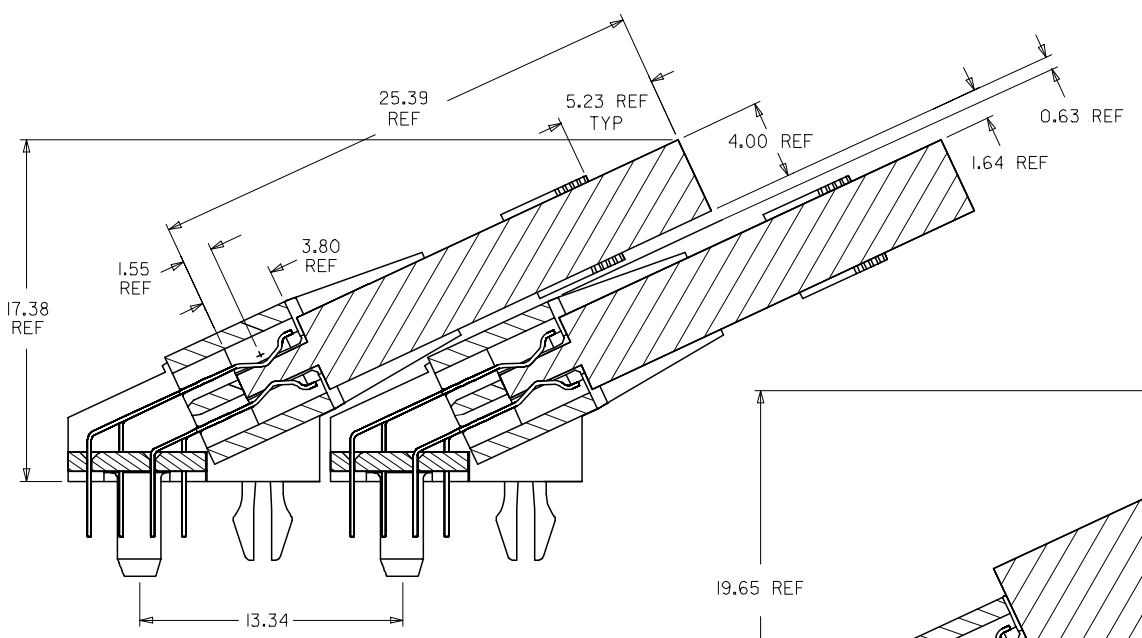
| | |
|----------------------------|------------|
| DIMENSION STYLE MM ONLY | |
| DRAWN BY | DATE |
| LPL IM | 2000/01/10 |
| CHECKED BY | DATE |
| DSOH | 2000/02/02 |
| APPROVED BY | DATE |
| SKTOH | 2000/02/02 |
| MATERIAL NO. | |
| SEE TABLE | |

| | | |
|---|------------------------|---------------------------|
| SCALE NTS | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| TITLE DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG. | | |
| MOLEX INCORPORATED | | |
| MATERIAL NO. | DOCUMENT NO. | SHEET NO. |
| SEE TABLE | SD-87623-001 | 1 OF 4 |
| THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | |

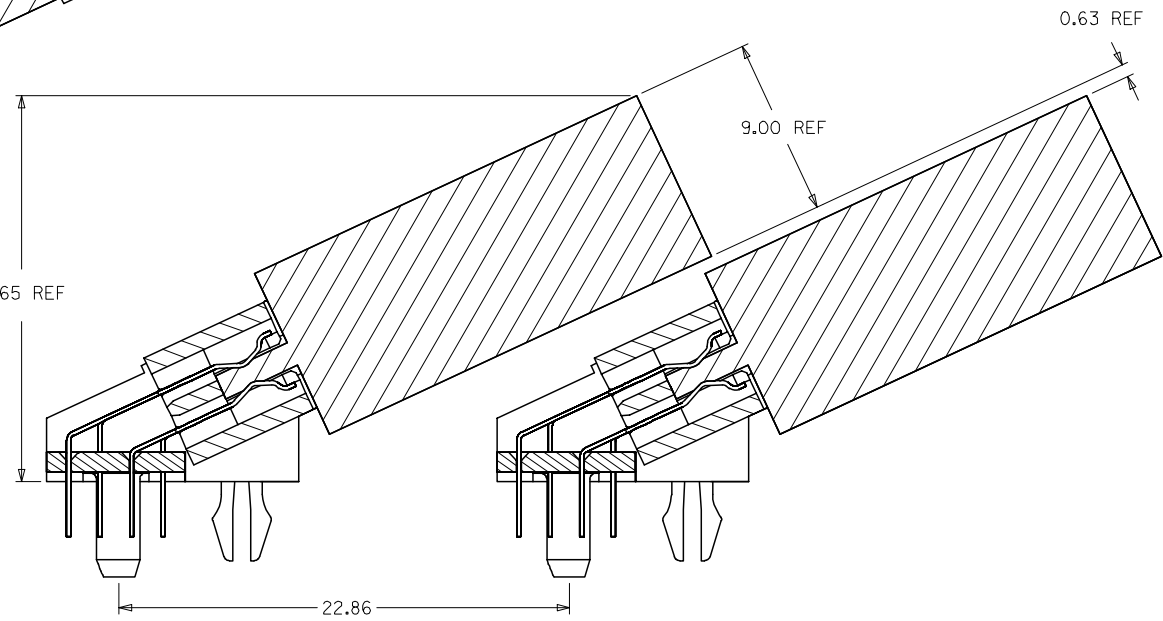
9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

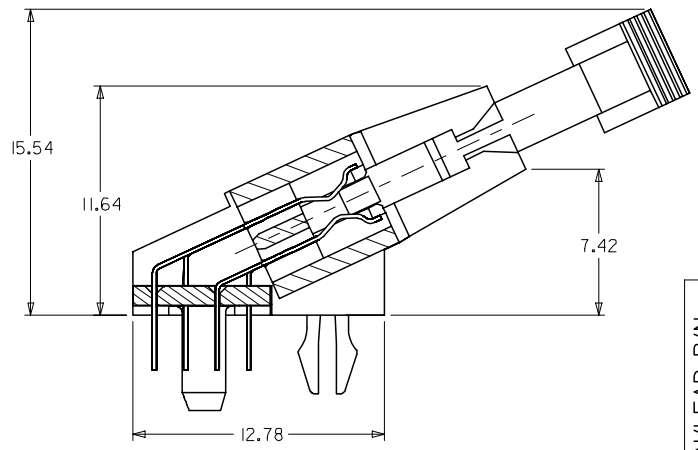
F
E
D
C
B
A



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00 mm THICK
MODULE (TYPICAL TSOP PACKAGING)



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 9.00 mm THICK
MODULE (TYPICAL SOJ PACKAGING)



SECTION A-A

OBS TIN/LEAD P/N
EC NO: S2006-0734
DRWN:MLONG
CHKD:IHO
APPR:GGLLEE

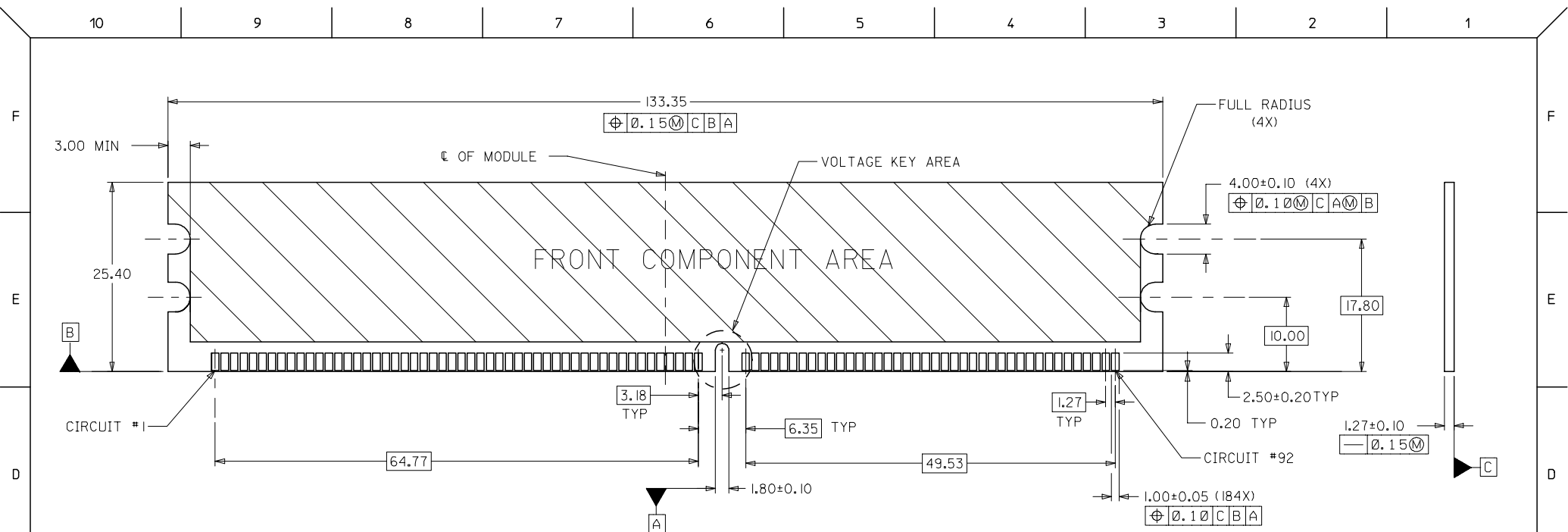
| REV | DESCRIPTION |
|-----|-----------------|
| 1 | QUALITY SYMBOLS |
| | ▽=0 |
| | ▽C=0 |

| GENERAL TOLERANCES (UNLESS SPECIFIED) | |
|--|--------|
| | mm |
| 4 PLACES | ± 0.25 |
| 3 PLACES | ± 0.25 |
| 2 PLACES | ± 0.25 |
| 1 PLACE | ± 0.25 |
| ANGULAR ± 5 ° | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | |

| DIMENSION STYLE | |
|-----------------|------------|
| MM ONLY | |
| DRAWN BY | DATE |
| LPL IM | 2000/01/10 |
| CHECKED BY | DATE |
| DSOH | 2000/02/02 |
| APPROVED BY | DATE |
| SKTOH | 2000/02/02 |
| MATERIAL NO. | |
| SEE TABLE | |
| SIZE | A3 |

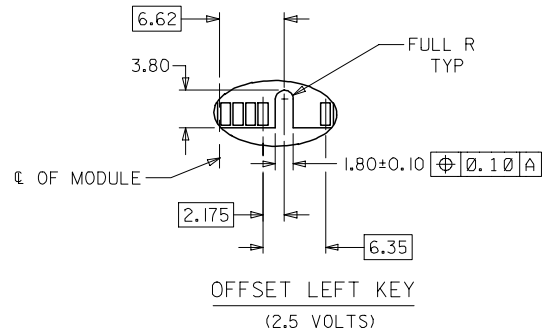
| | | | | |
|---|-----|---|--------------|------------------------|
| SCALE | NTS | DESIGN UNITS | METRIC | THIRD ANGLE PROJECTION |
| TITLE | | DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG. | | |
| MOLEX INCORPORATED | | DOCUMENT NO. | SD-87623-001 | |
| SHEET NO. | | 2 OF 4 | | |
| THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |

9 8 7 6 5 4 3 2 1



RECOMMENDED MODULE LAYOUT
 (PER JEDEC STANDARD MO-206, 184 CKT.)
 UNLESS OTHERWISE SPECIFIED, GENERAL TOLERANCE FOR MODULE = ±0.13

VOLTAGE KEY AREA



| | |
|-------------------|-------------|
| OBS TIN/LEAD P/N | 2006/02/27 |
| EC NO: S2006-0734 | 2006/02/28 |
| DRWN:MLONG | 2006/03/01 |
| CHKD:HO | |
| APPR:GGLLEE | |
| REV | DESCRIPTION |

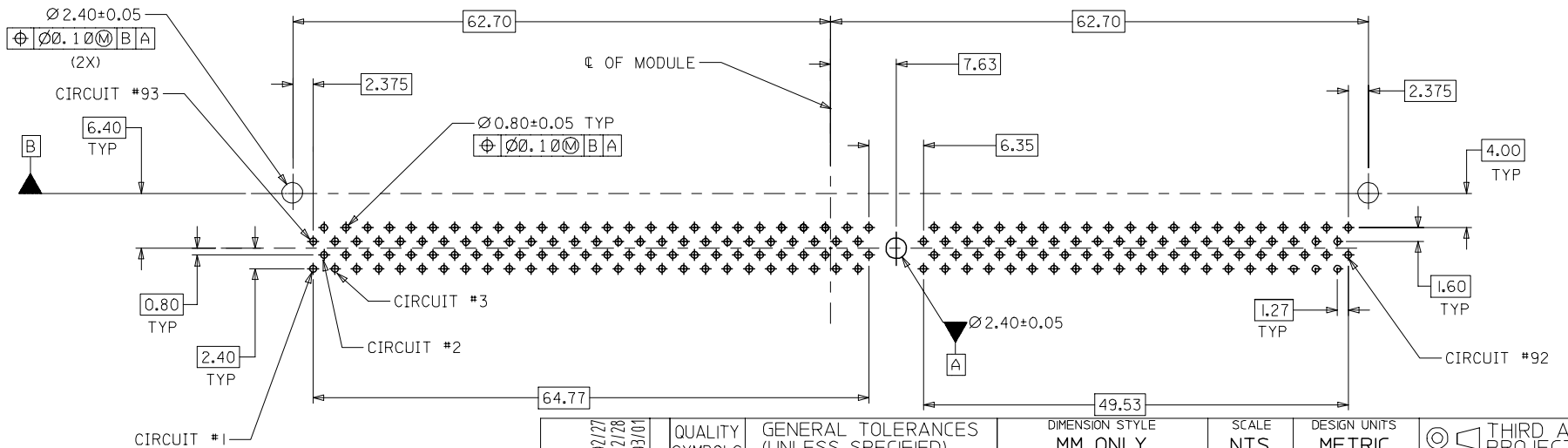
| | |
|-----------------|-----|
| QUALITY SYMBOLS | ▽=0 |
| | ∇=0 |

| | | |
|--|-----------------|-------|
| GENERAL TOLERANCES (UNLESS SPECIFIED) | mm | INCH |
| | 4 PLACES ± --- | ± --- |
| | 3 PLACES ± --- | ± --- |
| | 2 PLACES ± 0.25 | ± --- |
| | 1 PLACE ± --- | ± --- |
| | ANGULAR ± 5 ° | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | |

| | | | | |
|-----------------|--------------|------------------------|--------------|------------------------|
| DIMENSION STYLE | | SCALE | DESIGN UNITS | THIRD ANGLE PROJECTION |
| MM ONLY | | NTS | METRIC | |
| DRAWN BY | DATE | TITLE | | |
| LPL IM | 2000/01/10 | DDR DIMM, 1.27MM PITCH | | |
| CHECKED BY | DATE | 184 CKTS, 25 DEG. | | |
| DSOH | 2000/02/02 | | | |
| APPROVED BY | DATE | | | |
| SKTOH | 2000/02/02 | | | |
| MATERIAL NO. | DOCUMENT NO. | SHEET NO. | | |
| | SD-87623-001 | 3 OF 4 | | |

| | |
|--------------------|---|
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|--------------------|---|

| PART NUMBER | VOLTAGE KEY | CKT SIZE | TAIL LENGTH P±0.25 | PEG LENGTH 0±0.25 | FORK LENGTH R±0.25 | RECOMMENDED PCB THICKNESS | FINISHES: CONTACT AREA |
|-------------|-------------|----------|-----------------------|----------------------|-----------------------|------------------------------|--|
| 87623-2001 | LEFT (2.5V) | 184 | 2.79 | 3.18 | 3.18 | 1.57 | SELECTIVE GOLD 0.38µM/15µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL |
| 87623-2011 | | | 3.18 | 4.83 | 3.94 | | |
| 87623-2012 | | | 3.18 | 3.18 | 3.18 | | |
| 87623-2013 | | | 3.81 | 4.83 | 4.42 | 2.84 | |
| 87623-2101 | | | 2.79 | 3.18 | 3.18 | 1.57 | |
| 87623-2111 | | | 3.18 | 4.83 | 3.94 | | |
| 87623-2113 | | | 3.81 | 4.83 | 4.42 | | |
| 87623-2115 | | | 3.18 | 3.18 | 3.18 | 1.57 | SELECTIVE GOLD 0.76µM/30µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL |



RECOMMENDED
P.C. BOARD HOLE PATTERN
(CONNECTOR SIDE)

OBS TIN/LEAD P/N
EC NO: S2006-0734
DRWN:HLONG
CHKD:JHO
APPR:GJLEE

QUALITY SYMBOLS
▽=0
△=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

| | MM | INCH |
|---------------|--------|-------|
| 4 PLACES | ± --- | ± --- |
| 3 PLACES | ± --- | ± --- |
| 2 PLACES | ± 0.25 | ± --- |
| 1 PLACE | ± --- | ± --- |
| ANGULAR ± 5 ° | | |

DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

| DRAWN BY | DATE |
|-------------|------------|
| LPL IM | 2000/01/10 |
| CHECKED BY | DATE |
| DSOH | 2000/02/02 |
| APPROVED BY | DATE |
| SKTOH | 2000/02/02 |

MATERIAL NO. SEE TABLE

SCALE NTS
DESIGN UNITS METRIC
THIRD ANGLE PROJECTION

TITLE
DDR DIMM, 1.27MM PITCH
184 CKTS, 25 DEG.

MOLEX INCORPORATED

DOCUMENT NO. SD-87623-001
SHEET NO. 4 OF 4

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